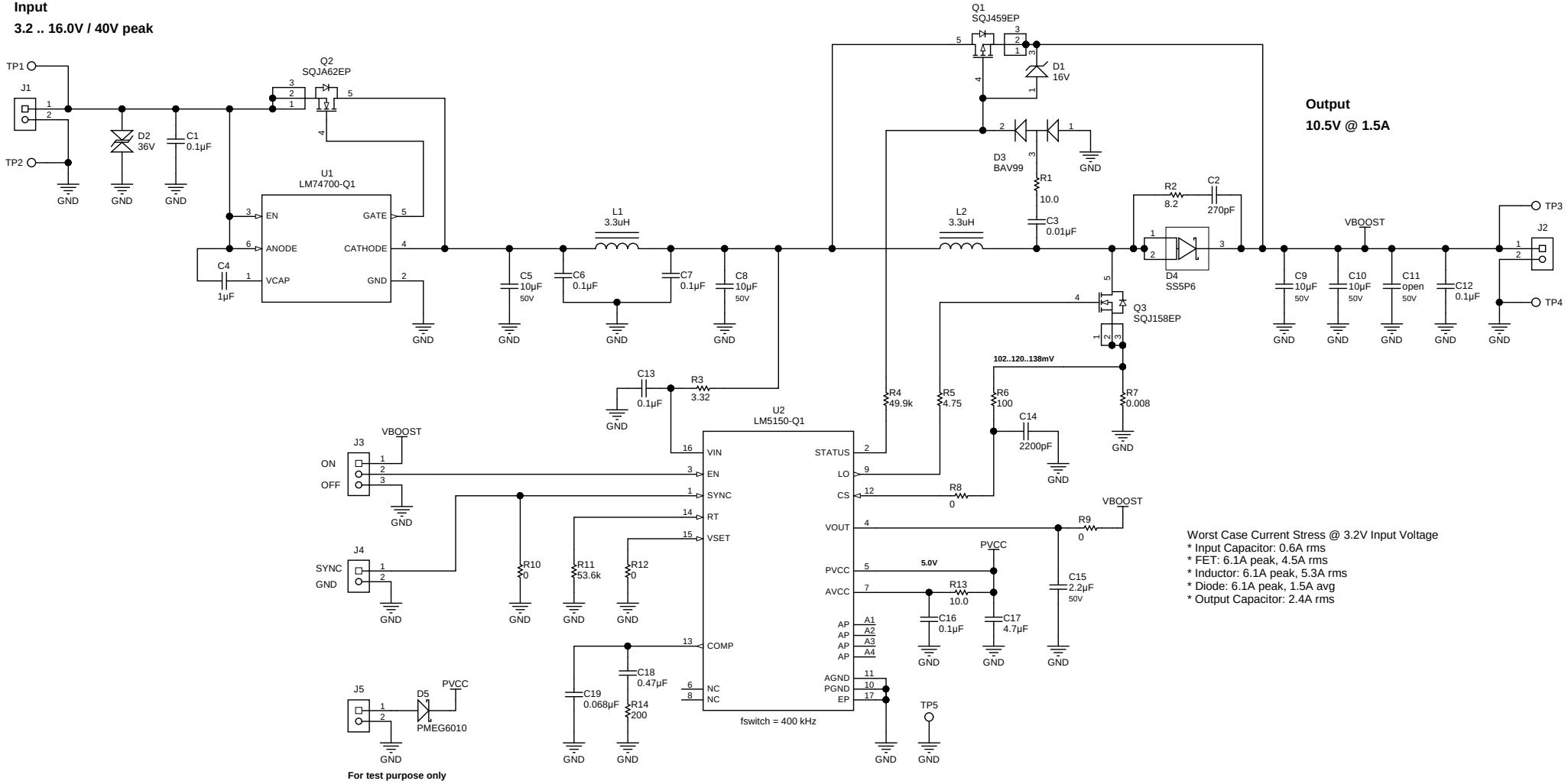
Revision History	
Revision	Notes
A	* Paper Design
B	* Layout
C	* Built & Tested

Input

3.2 .. 16.0V / 40V peak

Output

10.5V @ 1.5A



Worst Case Current Stress @ 3.2V Input Voltage
* Input Capacitor: 0.6A rms
* FET: 6.1A peak, 4.5A rms
* Inductor: 6.1A peak, 5.3A rms
* Diode: 6.1A peak, 1.5A avg
* Output Capacitor: 2.4A rms

Orderable: EVM_orderable		Designed for: Public Release	Mod. Date: 12/12/2017
TID #: TID		Project Title: Automotive Power Tree	
Number: PMP30267	Rev: C	Sheet Title:	
SVN Rev: Version control disabled		Assembly Variant: [No Variations]	Sheet: 1 of 2
Drawn By:		File: PMP30267RevC - Pre-Boost.SchDoc	Size: A3
Engineer: Matthias Ulmann		Contact: http://www.ti.com/support	

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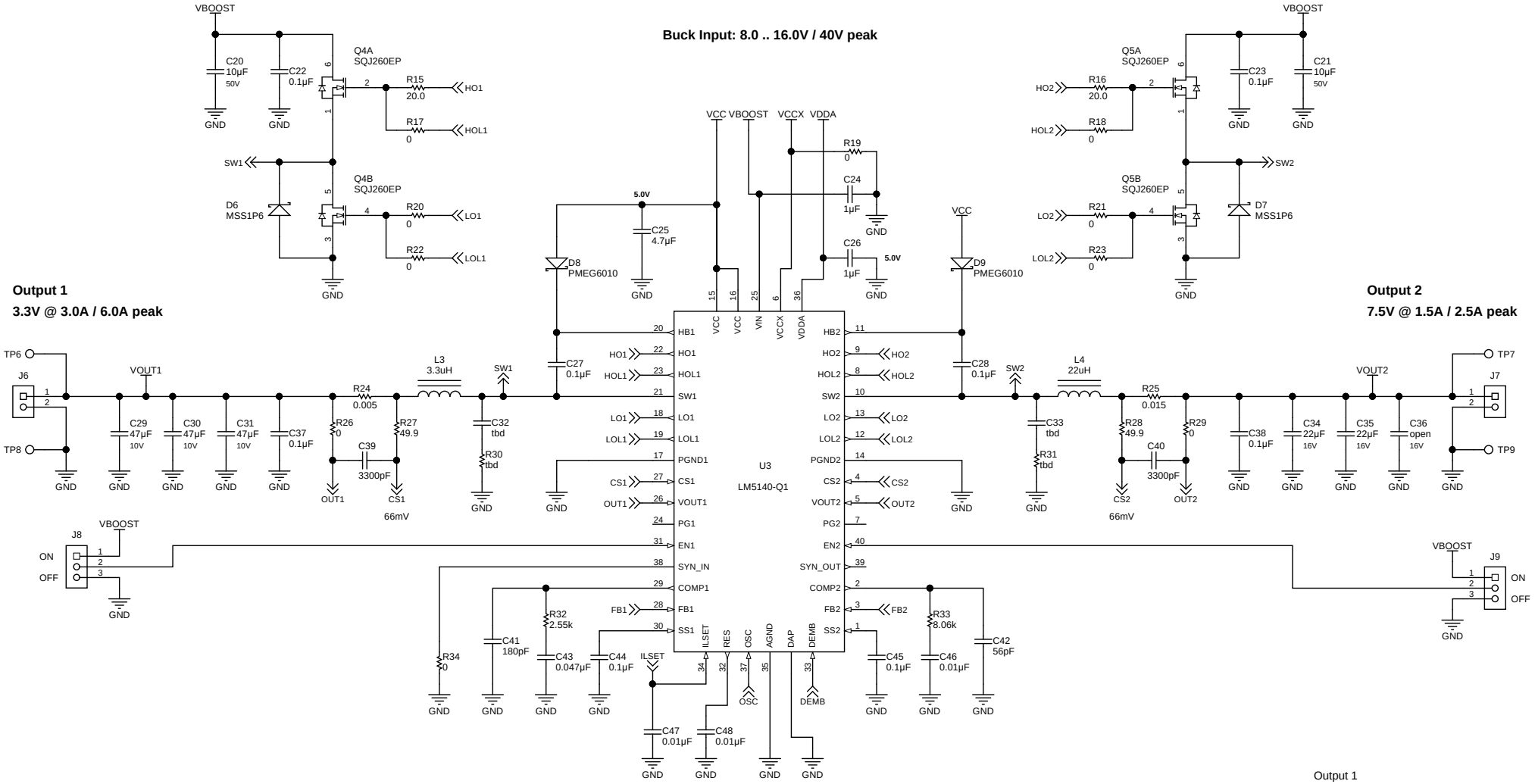

Output 1

Current Stress @ 5.0A Load
* Input Capacitor: 2.5A rms
* High-Side FET: 5.6A peak, 3.2A rms
* Low-Side FET: 5.6A peak, 4.5A rms
* Inductor: 5.6A peak, 5.0A rms
* Output Capacitor: 0.4A rms

Output 2

Current Stress @ 1.0A Load
* Input Capacitor: 0.5A rms
* High-Side FET: 1.1A peak, 1.0A rms
* Low-Side FET: 1.1A peak, 0.7A rms
* Inductor: 1.1A peak, 1.0A rms
* Output Capacitor: 0.1A rms

GND: 440 kHz
VDDA: 2.2 MHz

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Engineer: Matthias Ulmann		Contact: http://www.ti.com/support	

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